Singapore Asahi Chemical & Solder Industries Pte Ltd

Asahi Products-Solder Paste

ASAHI SOLDER — Connecting The World

	Formula Type	LF	LFH02	LF138	LFF1	5M097	LFB21	LF249	2T/5T
Product Features	**Alloy Compatibility**	V347/V349				SAC305	SACB1053	SAC105	SnPb/SnPbAg
		For standard stencil printing as well as paste-in-hole reflow application. It carries good dispensing, tackiness and drip-free characteristics.	For superior printing requirement. It provides hours of stable stencil life, tack time and repeatable brick definition.	Designed for environmental robustness in cold temperature and low humidity condition. This solder paste is formulated to reduce voiding in BGA solder.	Designed for water soluble application. It offers repeatable and consistent paste transfer volume, excellent solderability with reduced voiding.	Developed to have better wettability in reflow process. This alloy is designed to be substituted for Tin/Lead in all electronics assembly soldering operations.	Developed to have better wettability in reflow process. It is cost effective while shows comparable mechanical strength with SAC305.	Asahi solder paste was developed to have better wettability in reflow soldering process. It is cost effective while shows comparable mechanical strength with SAC305.	Specially formulated for Fine Pitch Surface Mount application where application pitch could be as fine as 12 mils pitch.
	Powder Type	Type 3	Type 3, Type 4	Type 3, Type 4, Type5	Type 3	Type 4	Type 4	Type 4	Type 3
Flux Content	**Type 3 (24-45μm)**	11.0 ± 0.5 wt%	11.0 ± 0.5 wt%	11.0 ± 0.5 wt%	12.0 ± 0.5 wt%	-	-	-	10.0 ± 0.5 wt%
	Type 4 (20-38μm)	-	11.0 ± 0.5 wt%	12.0 ± 0.5 wt%	-	11.5 ± 1.0 wt%	11.5 ± 0.5 wt%	11.5 ± 0.5 wt%	-
	Type 5 (15-25μm)	-	-	12.0 ± 0.5 wt%	-	-	-	-	-
Properties	**Viscosity** IPC-TM-650 2.4.34	780 ± 15% KcPs	800 ± 15% KcPs (Type 3) 800 ± 15% KcPs (Type 4)	750 ± 15% KcPs (Type 3) 700 ± 15% KcPs (Type 4) 750 ± 15% KcPs (Type 5)	600 ± 15% KcPs	750 ± 250 KcPs	680 ± 15% KcPs	650 ± 15% KcPs	1000 ± 15% KcPs
	Tackiness JIS Z 3284 Annex 9	>24 hrs (>100gf)	>24 hrs (>100gf)	>24 hrs (>100gf)	>24 hrs (>100gf)	>24 hrs (>100gf)	>24 hrs (>100gf)	>24 hrs (>100gf)	>24 hrs (>100gf)
	Slump Test JIS Z 3284 Annex 7, Annex 8	No Slump Observed	No Slump Observed	No Slump Observed	No Slump Observed	No Slump Observed	No Slump Observed	No Slump Observed	No Slump Observed
	Solder Ball Test JIS Z 3284 Annex 11	Passed	Passed	Passed	Passed	Passed	Passed	Passed	Passed
	Residue Dryness Test JIS Z 3284 Annex 12	Passed	Passed	Passed	Passed	Passed	Passed	Passed	Passed
	Halide Content JIS Z 3197 8.1.4.2.1	Not Added	Not Added	Not Added	< 0.05 wt%	Not Added	Not Added	Not Added	Not Added
	Halogen Content EN14582	Not Detected	Not Detected	Not Detected	< 0.05 wt%	Not Detected	Not Detected	Not Detected	Not Detected
	SIR (85°C, 85%RH, 168hrs) IPC-TM-650 2.6.3.3	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω
	ECM (85°C, 88.5%RH, 596hrs) IPC-TM-650 2.6.14.1	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth
	Flux Activity Classification IPC J-STD-004	ROL0	ROL0	ROL0	ROH0	ROL0	ROM0	ROM0	ROL0
	Residue Removal	Not Required	Not Required	Not Required	Rinse with DI water at 40°C-65°C	Not Required	Not Required	Not Required	Not Required
	Stencil Life	At least 24 hrs	At least 24 hrs	At least 24 hrs	At least 24 hrs	At least 24 hrs	At least 24 hrs	At least 24 hrs	At least 24 hrs
	Reflow Peak Temperature	≥220°C (V347) ≥225°C (V349)				≥235°C		≥240°C	≥205°C